MA2JF210G

Silicon epitaxial planar type

For bias winding rectification

■ Features

- Voltage rectification in bias winding

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	200	V
Non-repetitive peak reverse surge voltage	V_{RSM}	200	V
Forward current (Average) *1	$I_{F(AV)}$	0.3	A
Non-repetitive peak forward surge current *2	I_{FSM}	3.0	A
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–40 to +150	°C

Note) *1: Ambient temperature: $T_a = 90°C$, DC wave on, mounted on an alumina PC board

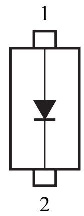
*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Package

- Code
  SMini2-F3
- Pin Name
  1: Anode
  2: Cathode

■ Marking Symbol: 1N

■ Internal Connection



■ Electrical Characteristics $T_a = 25°C±3°C$

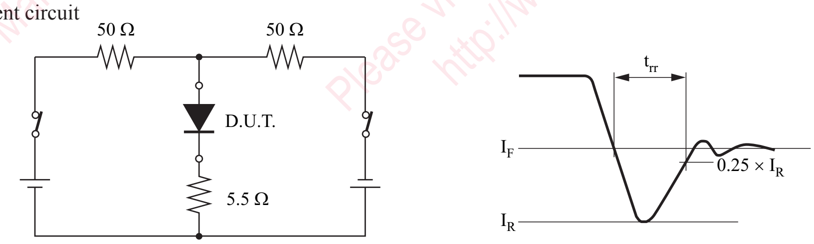
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 300$ mA			1.25	V
Reverse current	I_{RRM}	$V_{RRM} = 200$ V			1.0	μA
Terminal capacitance	C_t	$V_R = 0$ V, f = 1 MHz		2		pF
Reverse recovery time *1	t_{rr}	$I_F = 0.1$ A, $I_R = 0.2$ A, $I_{rr} = 0.05$ A		400		ns
Thermal resistance (ch-a) *2	$R_{th(j-a)}$	Mounted on an alumina PC board		160		°C/W

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 20 MHz

3. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

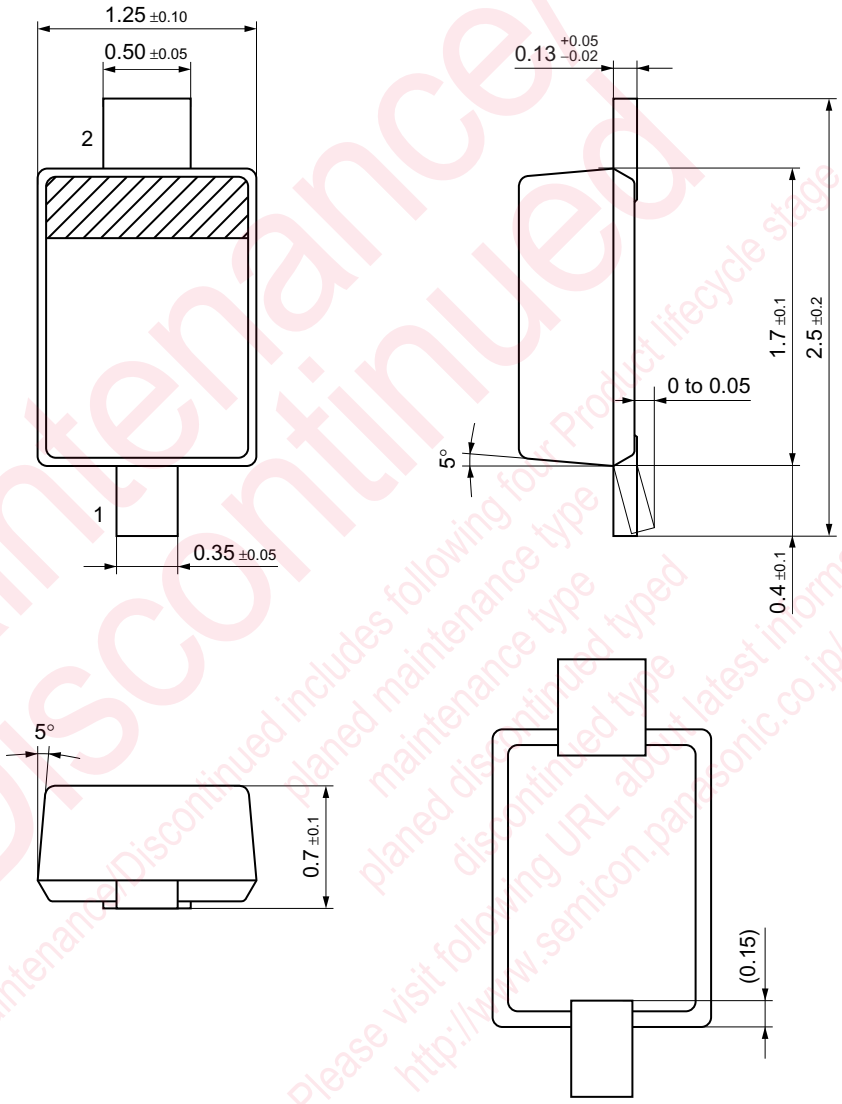
4. *1: t_{rr} measurement circuit



*2: Mounted on an alumina PC board (Board: 20 mm × 50 mm, Soldering land: 2 mm × 2 mm)

SMini2-F3

Unit: mm



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